

C4D02120E

Silicon Carbide Schottky Diode

Z-Rec® Rectifier

 V_{RRM} = 1200 V $I_{F}(T_{c}=135^{\circ}C)$ = 5 A Q_{c} = 11 nC

Features

- 1.2kV Schottky Rectifier
- Zero Reverse Recovery Current
- High-Frequency Operation
- Temperature-Independent Switching
- Extremely Fast Switching
- Positive Temperature Coefficient on V_F

Benefits

- Replace Bipolar with Unipolar Rectifiers
- Essentially No Switching Losses
- Higher Efficiency
- Reduction of Heat Sink Requirements
- Parallel Devices Without Thermal Runaway

Applications

- Switch Mode Power Supplies (SMPS)
- Boost Diodes in PFC or DC/DC stages
- Free Wheeling Diodes in Inverter stages
- LED Lighting Power Supplies
- AC/DC Converters

Package







TO-252-2



Part Number	Package	Marking
C4D02120E	TO-252-2	C4D02120

Maximum Ratings (T_c=25°C unless otherwise specified)

Symbol	Parameter	Value	Unit	Test Conditions	Note
V _{RRM}	Repetitive Peak Reverse Voltage	1200	V		
V _{RSM}	Surge Peak Reverse Voltage	1300	V		
V _{DC}	DC Blocking Voltage	1200	V		
I _F	Maximum DC Current	10 5 2	А	T _c =25°C T _c =135°C T _c =165°C	Fig. 3
\mathbf{I}_{FRM}	Repetitive Peak Forward Surge Current	13 8.4	Α	T_c =25°C, t_p =10 ms, Half Sine pulse T_c =110°C, t_p =10 ms, Half Sine pulse	
I_{FSM}	Non-Repetitive Peak Forward Surge Current	19 16.5	Α	T_c =25°C, t_p =10 ms, Half Sine pulse T_c =110°C, t_p =10 ms, Half Sine pulse	Fig. 8
I _{F,Max}	Non-Repetitive Peak Forward Current	200 160	Α	T_c =25°C, t_p =10 μ s, Pulse T_c =110°C, t_p =10 μ s, Pulse	Fig. 8
P _{tot}	Power Dissipation	60 26	W	T _c =25°C T _c =110°C	Fig. 4
dV/dt	Diode dV/dt ruggedness	200	V/ns	V _R =0-650V	
∫i²dt	i²t value	1.8 1.4	A²s	T_c =25°C, t_p =10 ms T_c =110°C, t_p =10 ms	
T _J , T _{stg}	Operating Junction and Storage Temperature	-55 to +175	°C		



Electrical Characteristics

Symbol	Parameter	Тур.	Max.	Unit	Test Conditions	Note
V _F	Forward Voltage	1.4 1.9	1.8 3	V	$I_F = 2 \text{ A } T_J = 25^{\circ}\text{C}$ $I_F = 2 \text{ A } T_J = 175^{\circ}\text{C}$	Fig. 1
I_R	Reverse Current	10 40	50 150	μΑ	$V_R = 1200 \text{ V } T_J = 25^{\circ}\text{C}$ $V_R = 1200 \text{ V } T_J = 175^{\circ}\text{C}$	Fig. 2
Q _c	Total Capacitive Charge	11		nC	$V_R = 800 \text{ V, } I_F = 2A$ $di/dt = 200 \text{ A/}\mu\text{s}$ $T_J = 25^{\circ}\text{C}$	Fig. 5
С	Total Capacitance	167 11 8		pF	$V_R = 0 \text{ V, } T_J = 25^{\circ}\text{C, } f = 1 \text{ MHz}$ $V_R = 400 \text{ V, } T_J = 25^{\circ}\text{C, } f = 1 \text{ MHz}$ $V_R = 800 \text{ V, } T_J = 25^{\circ}\text{C, } f = 1 \text{ MHz}$	Fig. 6
E _c	Capacitance Stored Energy	3.2		μЈ	V _R = 800 V	Fig. 7

Note: This is a majority carrier diode, so there is no reverse recovery charge.

Thermal Characteristics

Symbol	Parameter	Тур.	Unit	Note
$R_{_{\theta JC}}$	Thermal Resistance from Junction to Case	2.5	°C/W	Fig. 9

Typical Performance

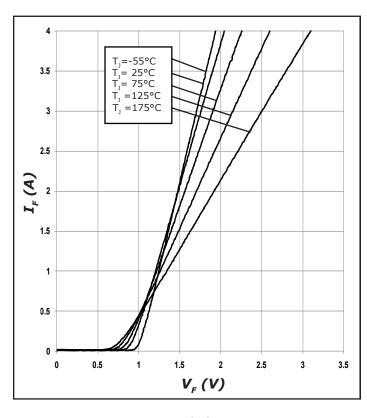


Figure 1. Forward Characteristics

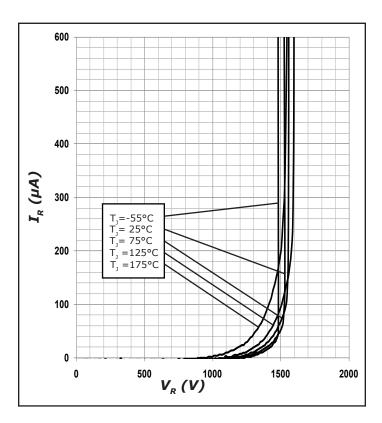


Figure 2. Reverse Characteristics



Typical Performance

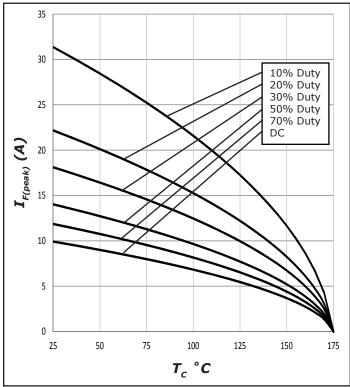


Figure 3. Current Derating

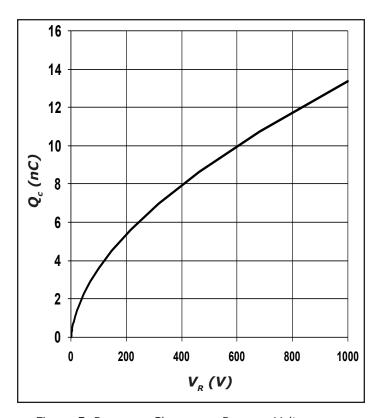


Figure 5. Recovery Charge vs. Reverse Voltage

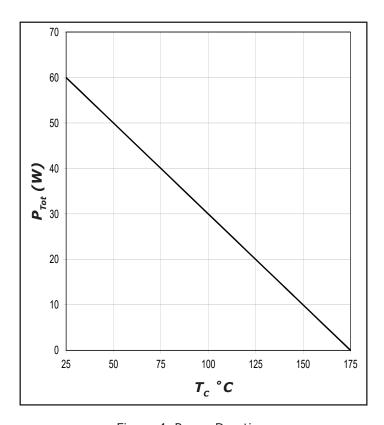


Figure 4. Power Derating

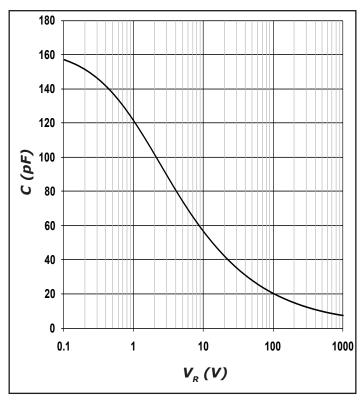


Figure 6. Capacitance vs. Reverse Voltage



Typical Performance

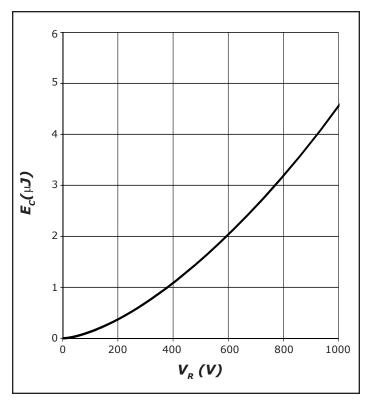


Figure 7. Typical Capacitance Stored Energy

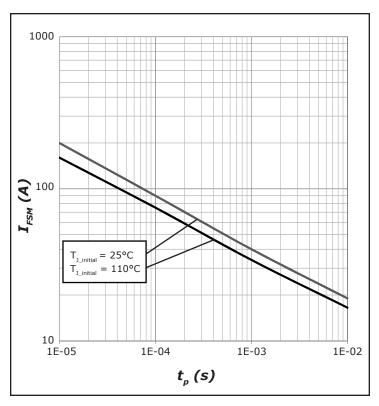


Figure 8. Non-repetitive peak forward surge current versus pulse duration (sinusoidal waveform)

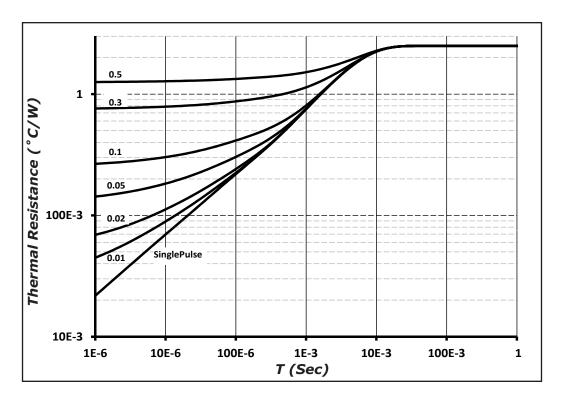
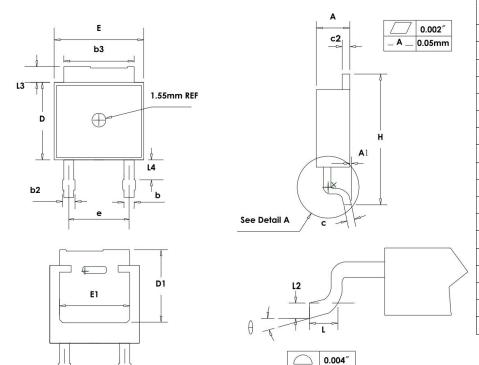


Figure 9. Transient Thermal Impedance



Package Dimensions

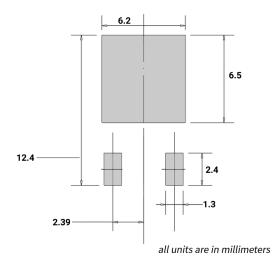
Package TO-252-2



SYMBOL	MILLIMETERS			
STIVIDOL	MIN	MAX		
А	2.159	2.413		
A1	0	0.13		
b	0.64	0.89		
b2	0.653	1.143		
b3	5.004	5.6		
С	0.457	0.61		
c2	0.457	0.864		
D	5.867	6.248		
D1	5.21	-		
Е	6.35	6.73		
E1	4.32	-		
е	4.58 BSC			
Н	9.65	10.414		
L	1.106	1.78		
L2	0.51 BSC			
L3 _O	0.889	1.27		
L4	0.64	1.01		
θ	0°	8°		



Recommended Solder Pad Layout



Part Number	Package	Marking
C4D02120E	TO-252-2	C4D02120

TO-252-2

Note: Recommended soldering profiles can be found in the applications note here: http://www.wolfspeed.com/power_app_notes/soldering

0.1mm





Diode Model

$$\begin{array}{c|c} - & & \\ \hline V_T & & R_T \\ \end{array}$$

$$V_{fT} = V_T + If * R_T$$

$$V_T = 0.9592 + (T_J^* -1.20^*10^{-3})$$

 $R_T = 0.1673 + (T_J^* 2.10^*10^{-3})$

Note: T₃ = Diode Junction Temperature in Degrees Celsius, valid from 25°C to 175°C

Notes

RoHS Compliance

The levels of RoHS restricted materials in this product are below the maximum concentration values (also referred to as the threshold limits) permitted for such substances, or are used in an exempted application, in accordance with EU Directive 2011/65/EC (RoHS2), as implemented January 2, 2013. RoHS Declarations for this product can be obtained from your Wolfspeed representative or from the Product Ecology section of our website at http://www.wolfspeed.com/power/tools-and-support/product-ecology.

• REACh Compliance

REACh substances of high concern (SVHCs) information is available for this product. Since the European Chemical Agency (ECHA) has published notice of their intent to frequently revise the SVHC listing for the foreseeable future, please contact a Cree representative to insure you get the most up-to-date REACh SVHC Declaration. REACh banned substance information (REACh Article 67) is also available upon request.

This product has not been designed or tested for use in, and is not intended for use in, applications implanted into
the human body nor in applications in which failure of the product could lead to death, personal injury or property
damage, including but not limited to equipment used in the operation of nuclear facilities, life-support machines,
cardiac defibrillators or similar emergency medical equipment, aircraft navigation or communication or control
systems, or air traffic control systems.

Related Links

- Cree SiC Schottky diode portfolio: http://www.wolfspeed.com/Power/Products#SiCSchottkyDiodes
- Schottky diode Spice models: http://www.wolfspeed.com/power/tools-and-support/DIODE-model-request2
- SiC MOSFET and diode reference designs: http://go.pardot.com/l/101562/2015-07-31/349i

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